

L Number	Hits	Search Text	DB	Time stamp
1	2834734	(semiconductor die chip mosfet schottky diode ic (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 06:40
2	271932	(ceramic insulated insulating) with (carrier substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 06:41
3	97251	((semiconductor die chip mosfet schottky diode ic (integrated adj circuit))) with ((ceramic insulated insulating) with (carrier substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 06:41
4	117982	((semiconductor die chip mosfet schottky diode ic (integrated adj circuit))) same ((ceramic insulated insulating) with (carrier substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 06:42
5	5573	wire same (((semiconductor die chip mosfet schottky diode ic (integrated adj circuit))) with ((ceramic insulated insulating) with (carrier substrate)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 06:42
6	7758	wire same (((semiconductor die chip mosfet schottky diode ic (integrated adj circuit))) same ((ceramic insulated insulating) with (carrier substrate)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 06:43
7	1266	(resin encapsulated encapsulation encapsulating epoxy) same (wire same (((semiconductor die chip mosfet schottky diode ic (integrated adj circuit))) with ((ceramic insulated insulating) with (carrier substrate))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 06:44
8	1884	(resin encapsulated encapsulation encapsulating epoxy) same (wire same (((semiconductor die chip mosfet schottky diode ic (integrated adj circuit))) same ((ceramic insulated insulating) with (carrier substrate))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 06:44
9	330	(expose exposing exposed external externally) same ((resin encapsulated encapsulation encapsulating epoxy) same (wire same (((semiconductor die chip mosfet schottky diode ic (integrated adj circuit))) with ((ceramic insulated insulating) with (carrier substrate))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 06:45
10	498	(expose exposing exposed external externally) same ((resin encapsulated encapsulation encapsulating epoxy) same (wire same (((semiconductor die chip mosfet schottky diode ic (integrated adj circuit))) same ((ceramic insulated insulating) with (carrier substrate))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 06:45